

## Features

- AEC-Q101 qualified
- Extremely low on-resistance  $R_{DS(on)}$
- Low reverse transfer capacitances
- 100% single pulse avalanche energy test
- 100%  $\Delta V_{DS}$  test
- Pb-Free plating / Halogen-Free / RoHS compliant

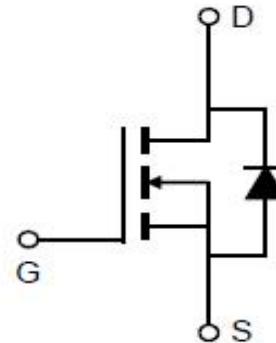
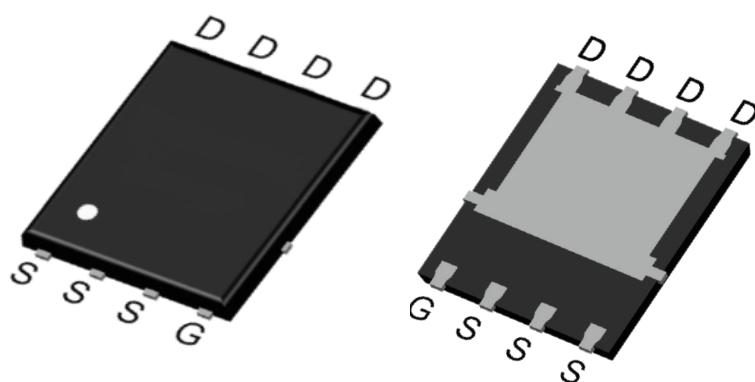
## Key Parameters

$V_{DS}$	40V
$R_{DS(on)typ.}$	0.8mΩ
$I_D$	340A
$C_{iss}@10V$	5275pF
$Q_{gd}$	7.3nC

## Applications

- Motor Control and Drive
- Charge/Discharge for Battery Management System
- Synchronous Rectifier for SMPS
- Automotive applications

**DFN5\*6**



## Marking & Packing Information

Part #	Package	Marking	Tube/Reel	Qty(pcs)
NVMFWS0D4N04XMT1G-CN	DFN5*6-8	009N04LA	Reel	3000/reel

**Absolute Maximum Ratings**

Parameter	Symbol	Value	Unit
Drain-source voltage	V <sub>DS</sub>	40	V
Gate-Source voltage	V <sub>GS</sub>	±20	V
Continuous drain current	I <sub>D</sub>	340	A
T <sub>C</sub> = 25°C		240	
T <sub>C</sub> = 100°C			
Pulsed drain current (T <sub>C</sub> = 25°C, t <sub>p</sub> limited by T <sub>jmax</sub> )	I <sub>D</sub> pulse	1360	A
Avalanche energy, single pulse (L=0.5mH, R <sub>g</sub> =25Ω)	E <sub>AS</sub>	900	mJ
Power dissipation	P <sub>tot</sub>	176	W
T <sub>A</sub> = 25°C		1.92	W
Operating junction and storage temperature	T <sub>j</sub> , T <sub>stg</sub>	-55...+175	°C

**Thermal Resistance**

Parameter	Symbol	Max	Unit
Thermal resistance, junction – case.	R <sub>thJC</sub>	0.85	°C/W
Thermal resistance, junction – ambient(min. footprint)	R <sub>thJA</sub>	78	

**Electrical Characteristic (at T<sub>j</sub> = 25 °C, unless otherwise specified)**
**Static Characteristic**

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Drain-source breakdown voltage	BV <sub>DSS</sub>	40	-	-	V	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA
Gate threshold voltage	V <sub>GS(th)</sub>	1.2	1.6	2.2	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA
Zero gate voltage drain current	I <sub>DSS</sub>	-	-	1	μA	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V
		-	-	100		T <sub>j</sub> =25°C
						T <sub>j</sub> =125°C
Gate-source leakage current	I <sub>GSS</sub>	-	-	100	nA	V <sub>GS</sub> =20V, V <sub>DS</sub> =0V
Drain-source on-state resistance	R <sub>DS(on)</sub>	-	0.8	0.95	mΩ	V <sub>GS</sub> =10V, I <sub>D</sub> =90A,
		-	1.2	1.6		T <sub>j</sub> =25°C
						V <sub>GS</sub> =4.5V, ID=90A

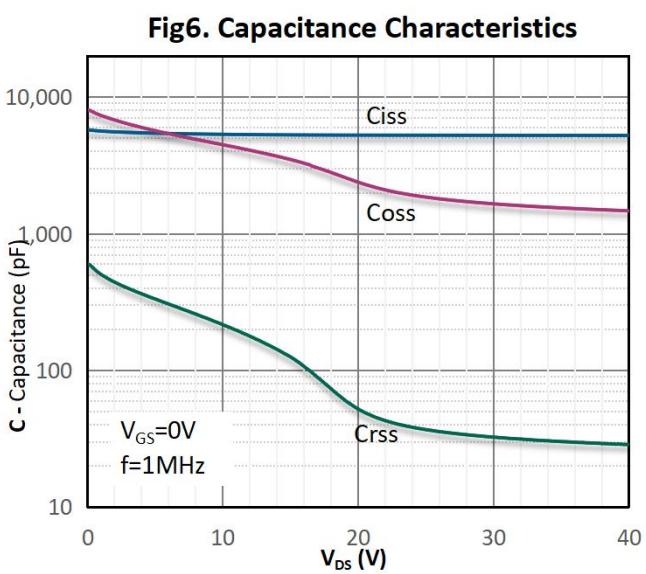
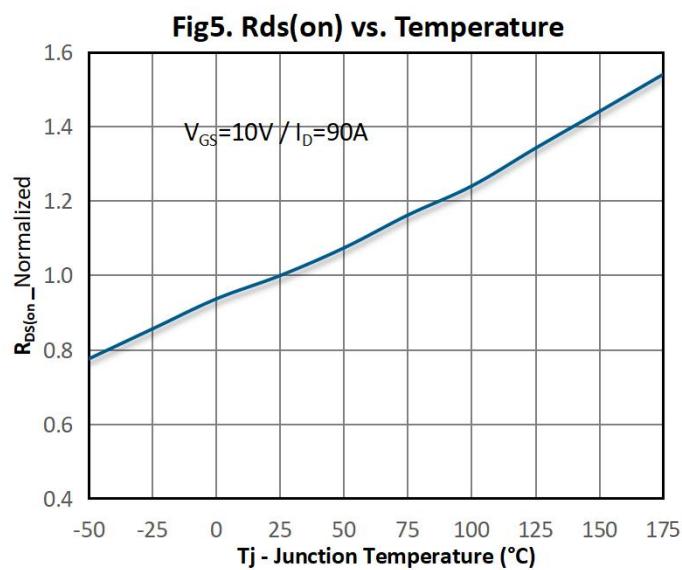
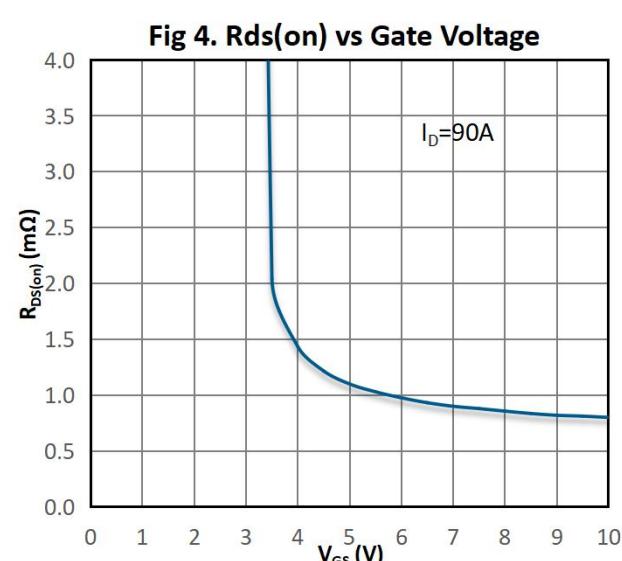
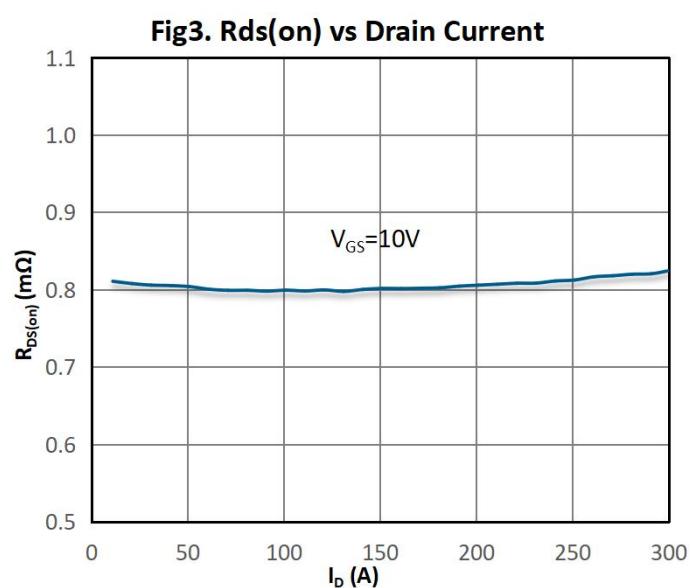
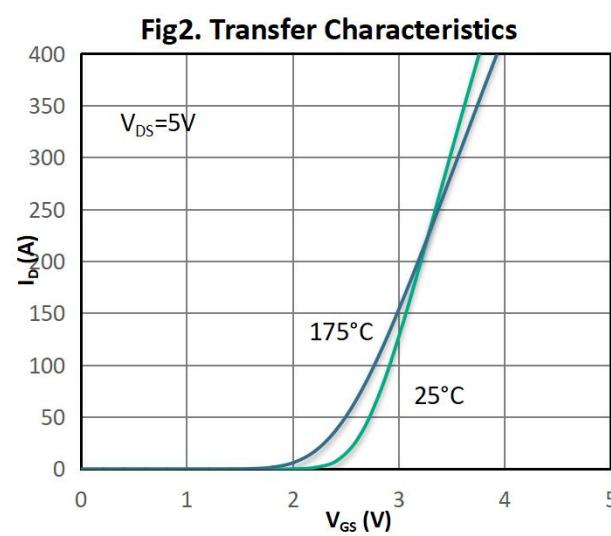
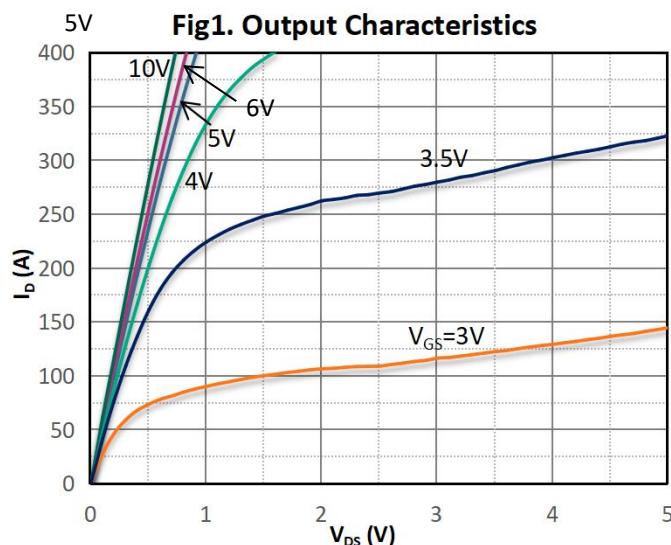
**Dynamic Characteristic**

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Input Capacitance	C <sub>iss</sub>	-	5275	-	pF	V <sub>GS</sub> =0V, V <sub>DS</sub> =20V, f=1MHz
Output Capacitance	C <sub>oss</sub>	-	2384	-		
Reverse Transfer Capacitance	C <sub>rss</sub>	-	52	-		
Gate Total Charge	Q <sub>G</sub>	-	71	-	nC	V <sub>GS</sub> =10V, V <sub>DS</sub> =20V, I <sub>D</sub> =90A, f=1MHz
Gate-Source charge	Q <sub>gs</sub>	-	17	-		
Gate-Drain charge	Q <sub>gd</sub>	-	7.3	-		
Turn-on delay time	t <sub>d(on)</sub>	-	10	-	ns	V <sub>GS</sub> =10V, V <sub>DD</sub> =20V, R <sub>G ext</sub> =3Ω, ID=90A
Rise time	t <sub>r</sub>	-	9	-		
Turn-off delay time	t <sub>d(off)</sub>	-	72	-		
Fall time	t <sub>f</sub>	-	60	-		
Gate resistance	R <sub>G</sub>	-	3.0	-	Ω	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz

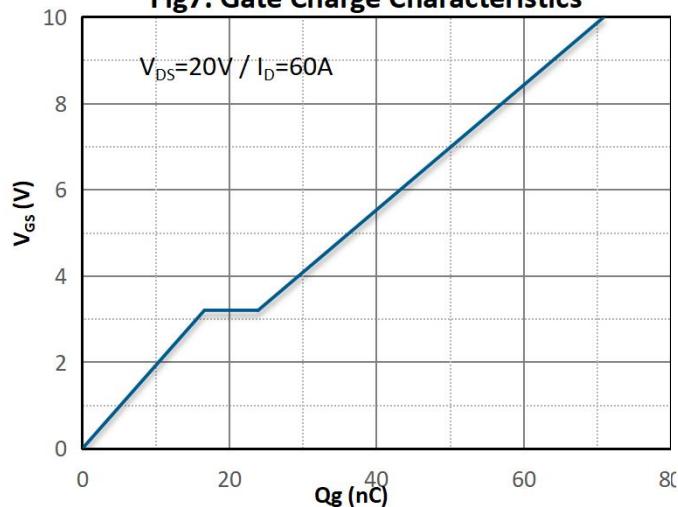
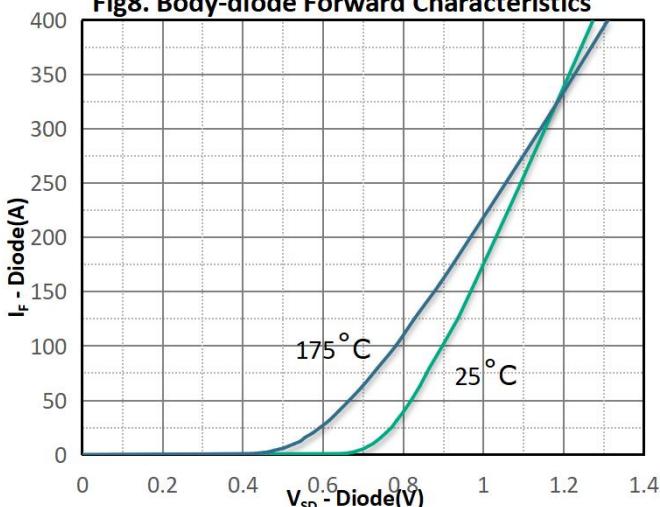
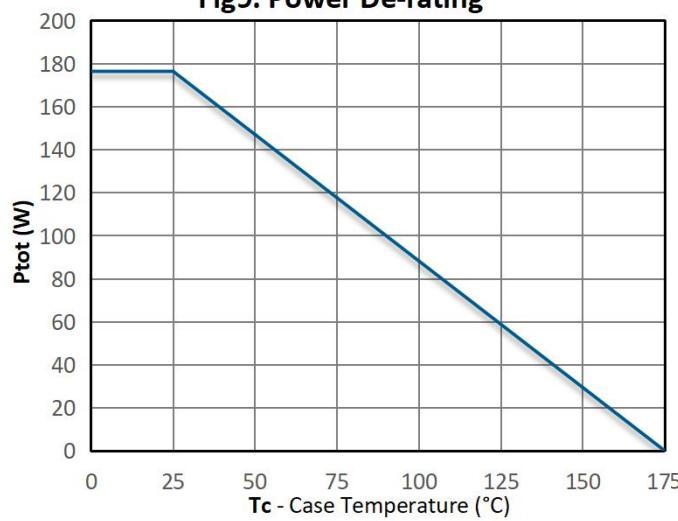
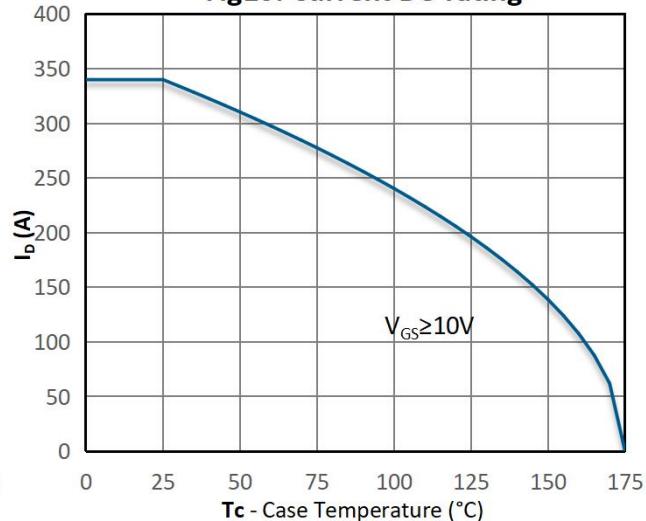
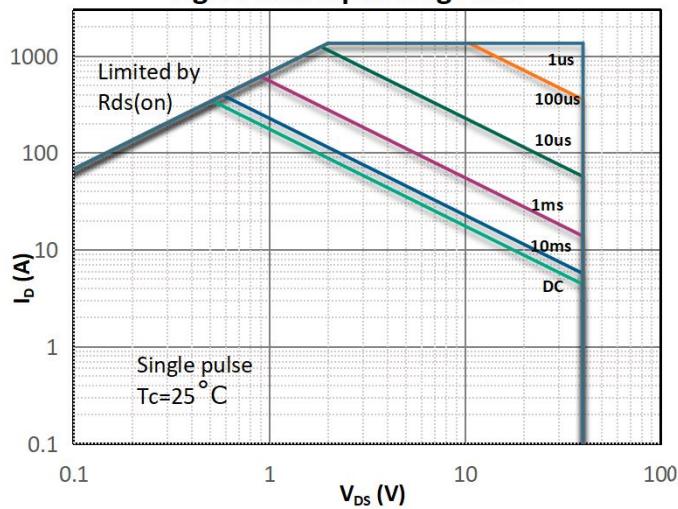
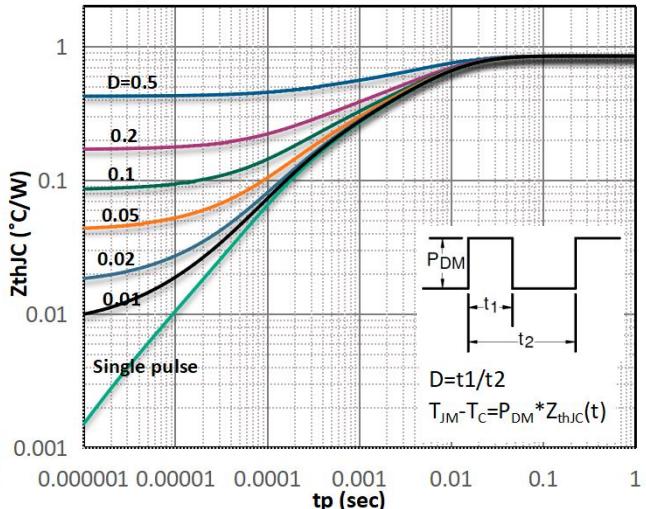
**Body Diode Characteristic**

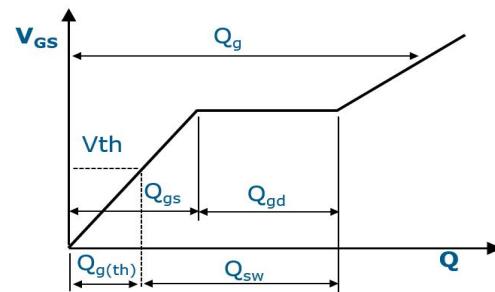
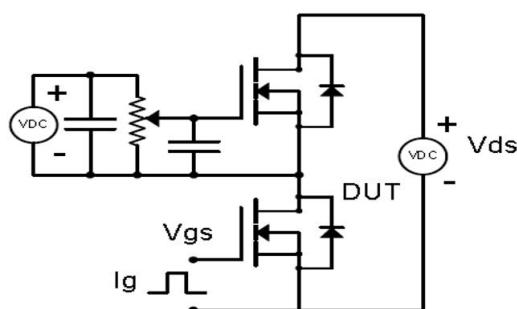
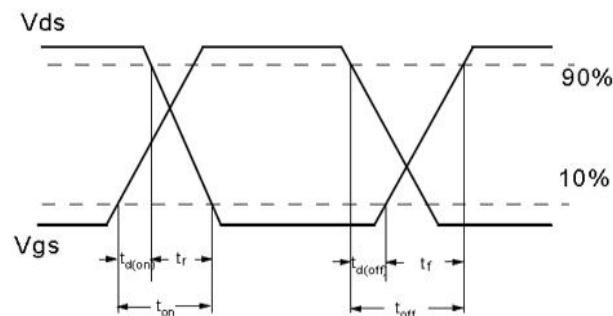
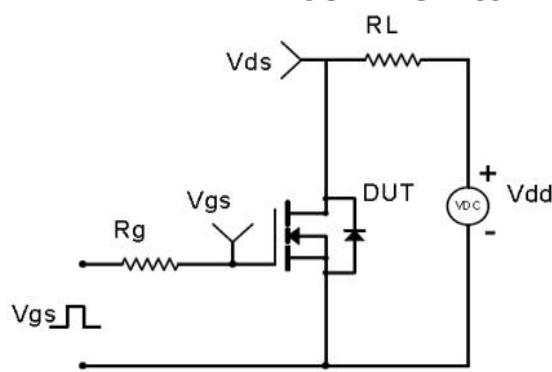
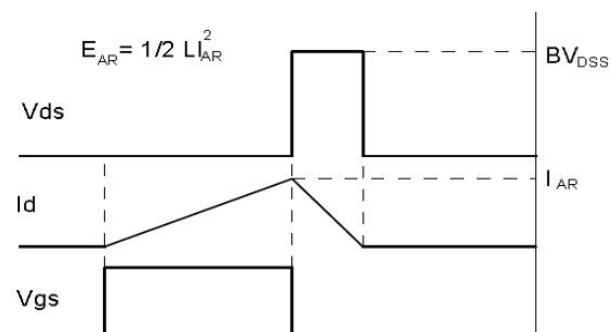
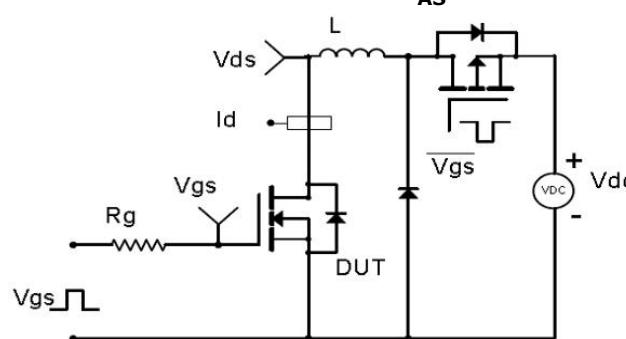
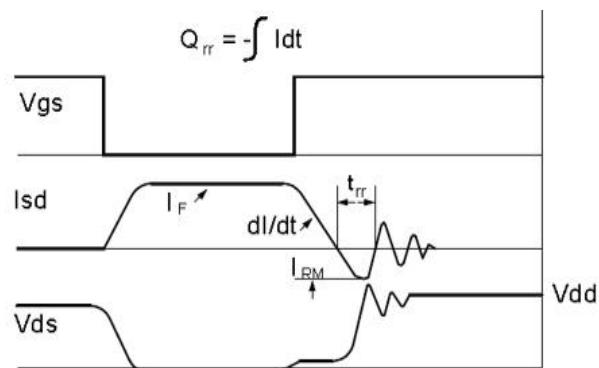
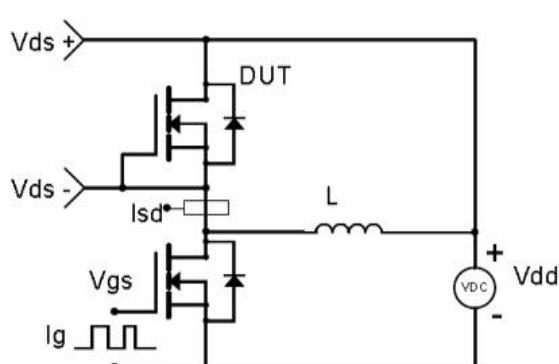
Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Diode Max Current	I <sub>S</sub>		-	340	A	-
Diode Forward Voltage	V <sub>SD</sub>	-	-	1.2	V	V <sub>GS</sub> =0V, I <sub>SD</sub> =100A
Diode Reverse Recovery Time	t <sub>rr</sub>	-	143	-	ns	I <sub>F</sub> =90A, dI/dt=100A/μs
Diode Reverse Recovery Charge	Q <sub>rr</sub>	-	135	-		

### Typical Characteristics Diagram



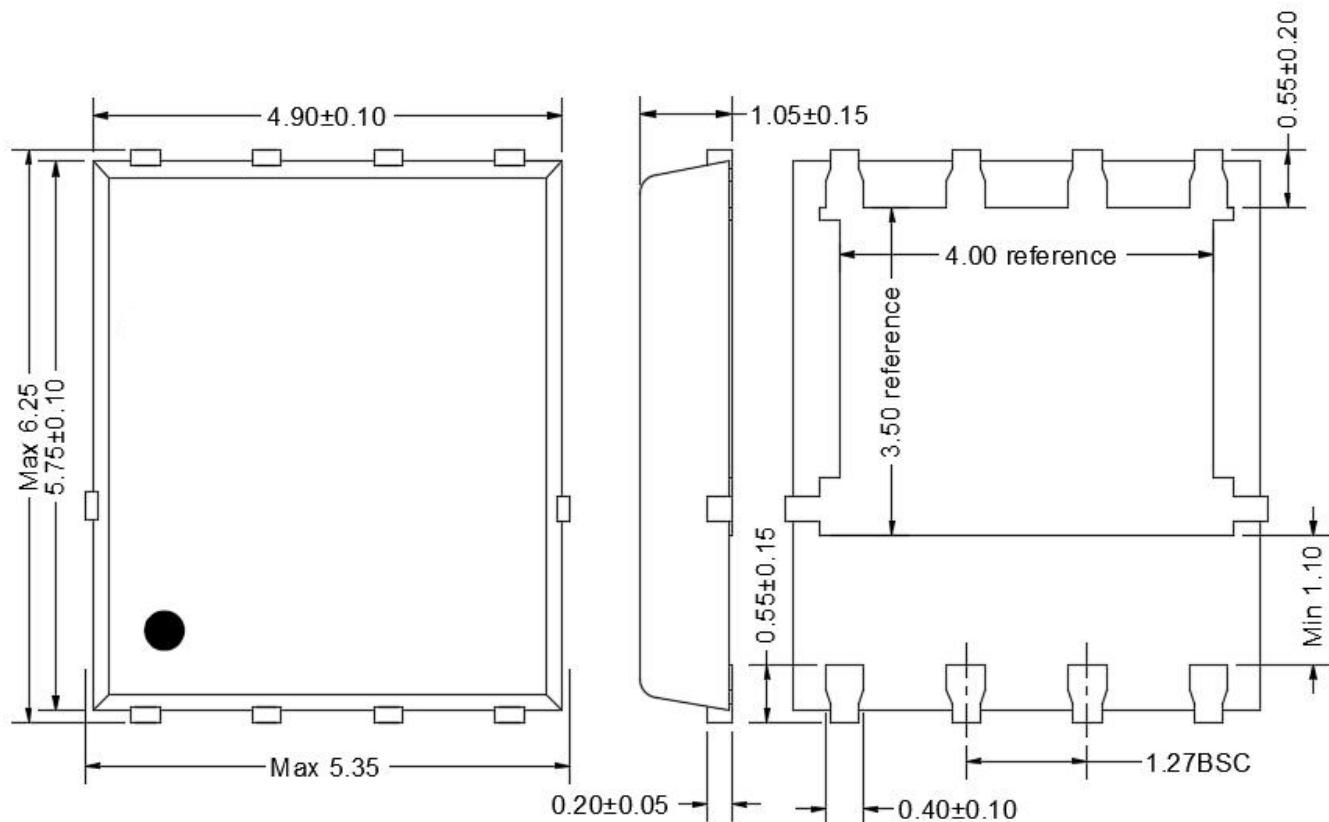
### Typical Characteristics Diagram

**Fig7. Gate Charge Characteristics**

**Fig8. Body-diode Forward Characteristics**

**Fig9. Power De-rating**

**Fig10. Current De-rating**

**Fig11. Safe Operating Area**

**Fig12. Max. Transient Thermal Impedance**


**Test Circuit & Waveform**
**Gate Charge Test Circuit & Waveform**

**MOSFET Switching Test Circuit & Waveform**

**E<sub>AS</sub> Test Circuit & Waveform**

**Diode Recovery Test Circuit & Waveform**


**Package Outline : DFN5\*6-8**

\*Dimensions in mm



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